section. (Please note that the section below includes the revision made to the Specification in the November 21, 2001 Amendment and Petition for Extension of Time.) A marked-up copy of this section, showing the changes made thereto, is attached.

--The input electrodes and the output electrodes of each driver IC 5p are connected to the copper foil electrodes 17 and 32 on the input side and output side TCPs 4a, respective via gold bumps 15p. The connections of each driver IC 5p are sealed with a resinous sealing agent 16p. In such a display panel connection structure for a display apparatus as shown in Figures 12 and 13, as the display panel (particularly a liquid crystal panel) is provided with a larger number of display electrodes at a higher density, the connection pitch for connection between the output electrodes of the TCPs and the electrode terminals on the transparent substrates are decreased down to a required pitch of 50 μm or smaller. However, according to a method for connecting TCP with a substrate as explained with reference to Figures 12 and 13, a very sophisticated and accurate bonding technique is required for ensuring such a minute connection pitch because of a limitation in size accuracy of TCPs and a deviation due to thermal expansion during connection by heat bonding of TCPs. Therefore, a connection structure as shown in Figure 14 including bonding of driver ICs 5 to a substrate 1bp by a face-down mode

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